



<b>Title of Change:</b>	Update Notice of IPCN20966X - Modify the qualification plan for matching it original products quality.
<b>Proposed first ship date:</b>	11 November 2016
<b>Contact information:</b>	Contact your local ON Semiconductor Sales Office or < Osamu.Akaki@onsemi.com>
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office
<b>Additional Reliability Data:</b>	Contact your local ON Semiconductor Sales Office or < Kazutoshi.Kitazume@onsemi.com>.
<b>Type of notification:</b>	ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
<b>Change category:</b>	<input checked="" type="checkbox"/> Wafer Fab Change <input type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____

<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Datasheet/Product Doc change
<input checked="" type="checkbox"/> Manufacturing Site Change/Addition <input type="checkbox"/> Material Change	<input type="checkbox"/> Shipping/Packaging/Marking
<input type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Product specific change	<input type="checkbox"/> Other: _____

<b>Sites Affected:</b>	<input type="checkbox"/> All site(s) <input type="checkbox"/> not applicable <input type="checkbox"/> ON Semiconductor site(s) :	<input checked="" type="checkbox"/> External Foundry/Subcon site(s) Maxchip Electronics Corp.
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**Description and Purpose:**

This Update Notice is issued to announce the modification on the qualification plan for matching it original products quality. Qualification tests are designed to show that the reliability of transferred devices will continue to meet or exceed original products.

1. IOL (Intermittent Operating Life) was deleted and switched to SSOL (Steady State Operating Life).
2. TC(Temperature Cycling) from 500cyc to 100cyc

IPCN20966X was previously issued to announce the addition of Maxchip Electronics Corp. (MXP) as a wafer fab site for the list of affected devices below. Maxchip Electronics Corp. (MXP) is located in Hsinchu, Taiwan, and is ISO9001 certified.

Test	Specification	Conditions	Interval
AC(AUTOCLAVE)	JESD22-A102	121°C, RH=100%,15psig	96Hrs
H3TRB(High Temperature High Humidity Reverse Bias)	JESD22-A101	85°C, RH=85%,VDSS=19.2V	504Hrs
HTGB(High Temperature Reverse Gate Bias)	JESD22-A108	Ta=150°C, VGSS=12.5V	504Hrs
HTRB(High Temperature Reverse Bias)	JESD22-A108	Ta=150°C, VDSS=19.2V	504Hrs
HTSL(High Temperature Storage Life)	JESD22-A103	Ta=150°C	504Hrs
SSOL(Steady State Operating Life)	JESD22-A108	Tj=150°C , VDS=16.8V	1008Hrs
RSH( Resistance to Soldering heat(Reflow))	JESD22- B106	Solder Temp.:260degC±5degC	10sec
TC(Temperature Cycling)	JESD22-A104	Ta=-55°C to 150°C	100cycles

**List of Affected Standard Parts:**

Part Number	Qualification Vehicle
ECH8693R-TL-W	ECH8693R-TL-W
ECH8695R-TL-W	ECH8693R-TL-W
ECH8697R-TL-W	ECH8693R-TL-W